

OSS70R350DF

Enhancement Mode N-Channel Power MOSFET



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	700	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	12	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		7.6	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	36	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	12	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S, \text{pulse}}$	36	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	83	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	160	
MOSFET dv/dt ruggedness, $V_{DS} = 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} = 480\text{ V}, I_{SD} = 0$	dv/dt	15	V/ns
Operation and storage temperature	T		

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		... 1		pF	V _{GS} =0 V, V _{DS} =50 V, 00 kHz
Output capacitance	C _{oss}		61.6		pF	
Reverse transfer capacitance	C _{rss}		3.1		pF	
Turn-on delay time	t _{d(on)}		24.7		ns	V _{GS} =10 V, V _{DS} =400 V, R _G I _D =6 A
Rise time	t _r		28		ns	
Turn-off delay time	t _{d(off)}		44.2		ns	
Fall time	t _f		18.4		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		9.8		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =6 A
Gate-source charge	Q _{gs}		4.5		nC	
Gate-drain charge	Q _{gd}		1.5		nC	
Gate plateau voltage	V _{plateau}		6.2		V	

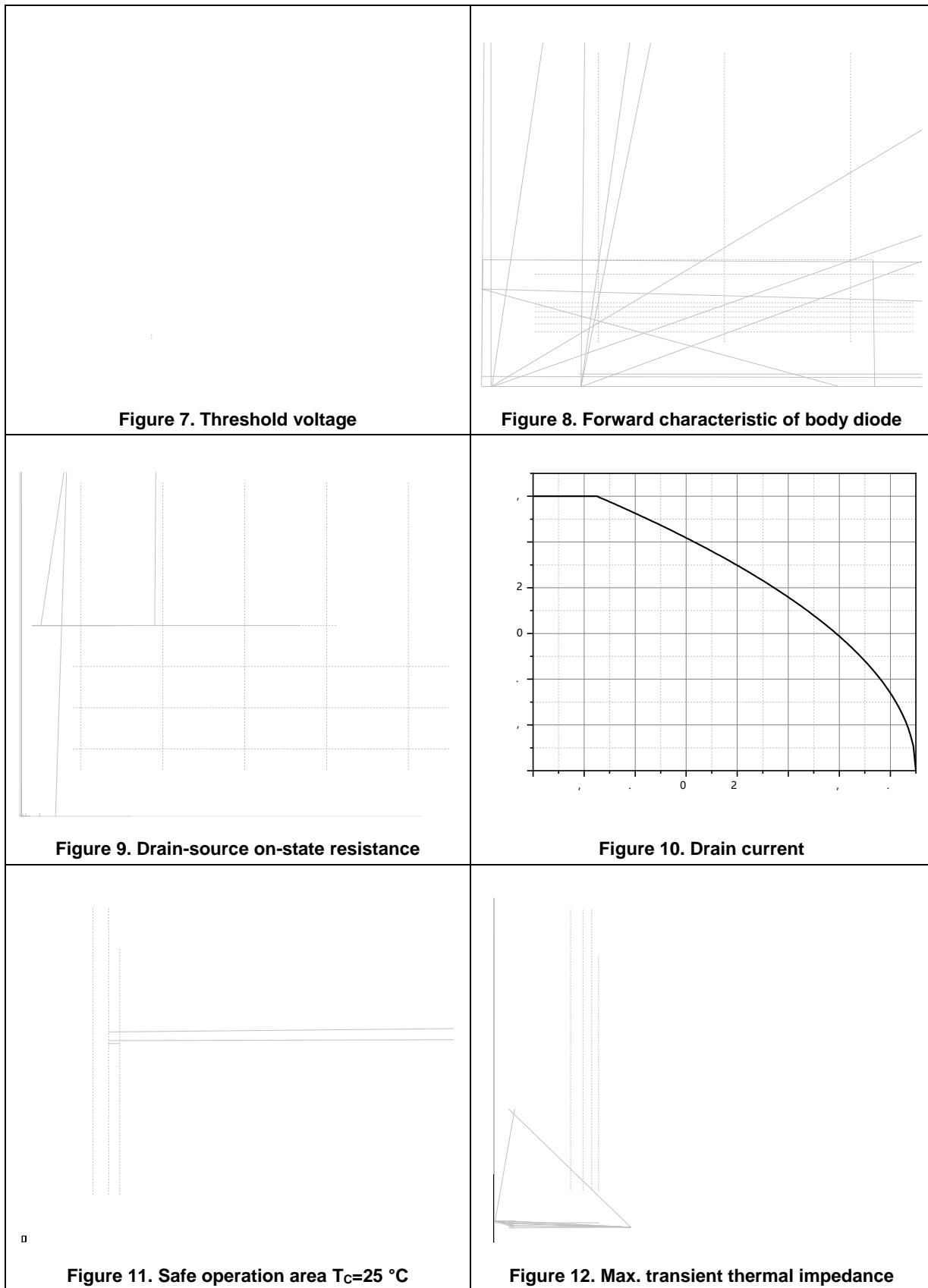
Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =12 A, V _{GS} =0 V I _S =6 A, di/dt
Reverse recovery time	t _{rr}		251		ns	
Reverse recovery charge	Q _{rr}		2.4		C	
Peak reverse recovery current	I _{rrm}		19.1		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_d is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C BDC 0.000008871 0 595.32 841.92 reW*nBT/F3 9.96 Tf1 0 0 1 69.024 2360

Electrical Characteristics Diagrams**Figure 1. Typ. output characteristics****Figure 2. Typ. transfer characteristics****Figure 3. Typ. capacitances****Figure 4. Typ. gate charge**



Test circuits and waveforms

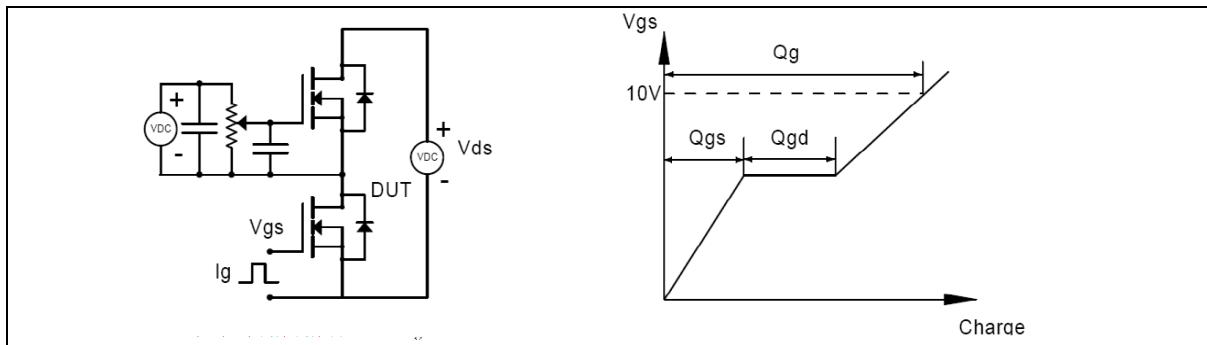


Figure 1. Gate charge test circuit & waveform

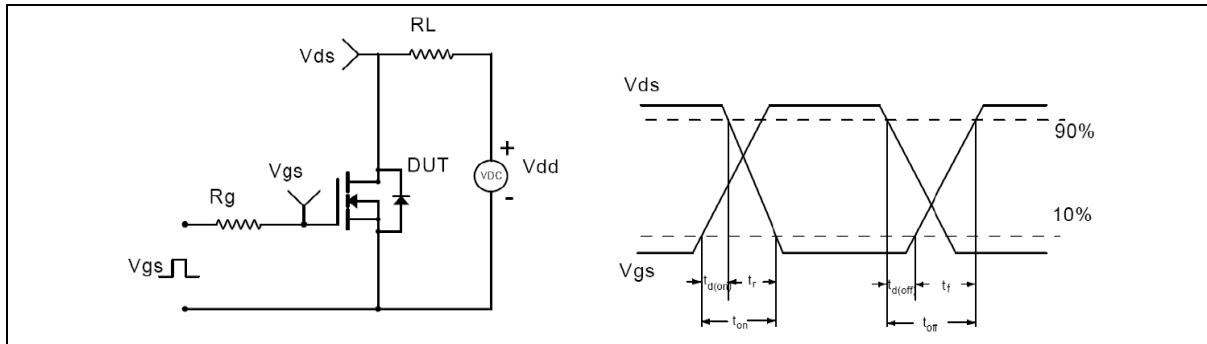


Figure 2. Switching time test circuit & waveforms

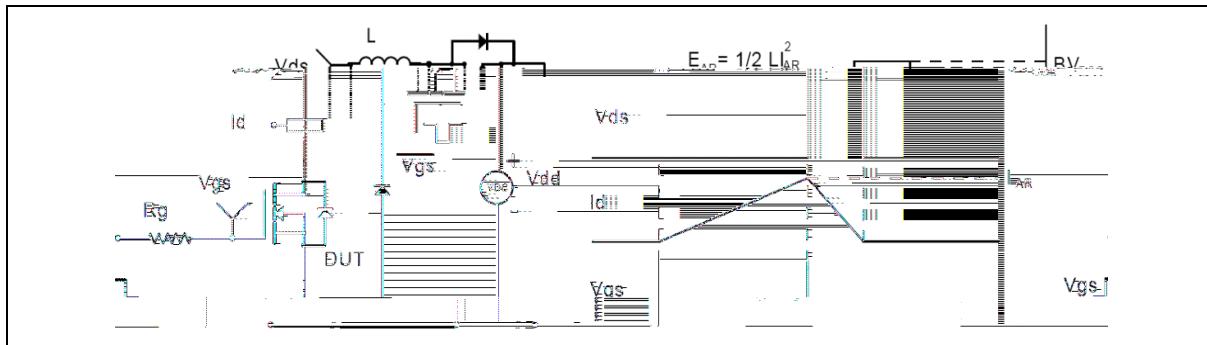
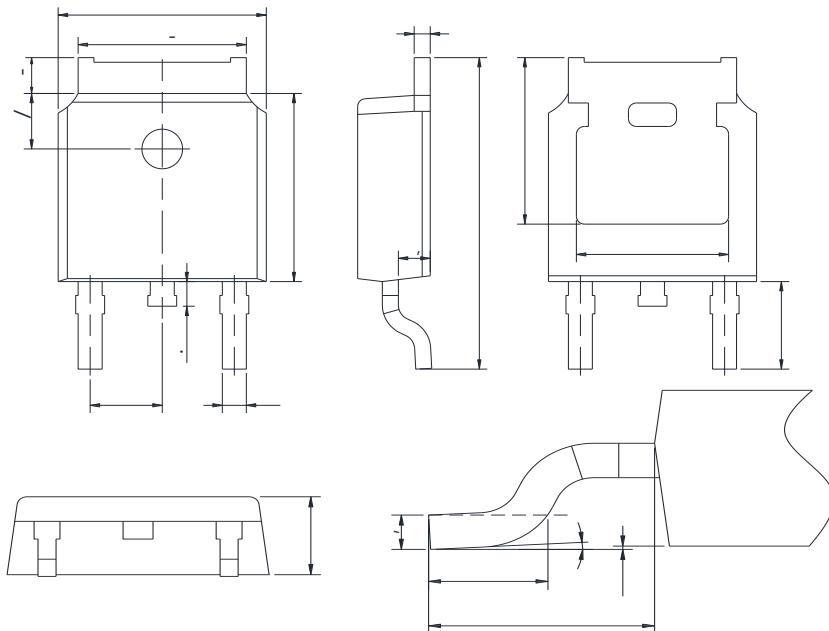


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms



Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.38
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
	0	-	

Version 1: TO252-C package outline dimension

Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO252-C	2500	2	5000	5	25000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSS70R350DF	TO252	yes	yes	yes

